DESCRIPTION

The AM2301A is available in SOT-23S package.

FEATURES

- V_{DS} =-20V
- $R_{DS(ON)}$, V_{GS} @-4.5V, I_{DS} @-4.7A=70 $m\Omega$
- $R_{DS(ON)}, V_{GS}@-2.5V, I_{DS}@-1.0A=110m\Omega$
- Available in SOT-23S Package

ORDERING INFORMATION

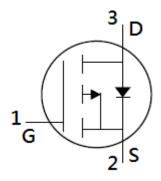
Package Type	Part Number			
SOT-23S	E3S	AM2301AE3SR		
		AM2301AE3SVR		
Nieto	V: Halogen free Package			
Note	R: Tape & Reel			
AiT provides all RoHS products				

Suffix "V" means Halogen free Package

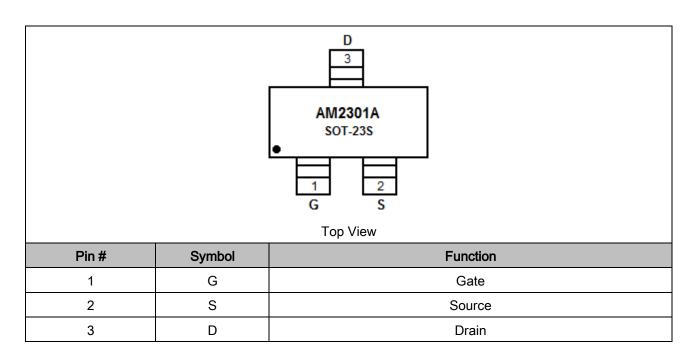
APPLICATION

- Advanced trench process technology
- High Density Cell Design For Ultra Low On-Resistance
- ESD Rating of Class 0 (<100V) per Human Body Model

PIN DESCRIPTION



PIN DESCRIPTION



ABSOLUTE MAXIMUM RATINGS

T.- 25

1A= 25		
V _{DSS} , Drain-to-Source Voltage		-20V
V _{GS} , Gate-to-Source Voltage		±12V
I _D , Continuous Drain Current		-4.7A
I _{DM} , Pulsed Drain Current ^{NOTE1}		-20A
D. Marianan Barras Dississation	T _A =25°C	1.1W
P _D , Maximum Power Dissipation	T _A =70°C	0.70W
T _J , T _{STG} , Operation and Storage Temperature Range		−55 ~ +150°C
R _{0JA} , Thermal Resistance-Junction to Ambient NOTE2		110°C/W

Stress beyond above listed "Absolute Maximum Ratings" may lead permanent damage to the device. These are stress ratings only and operations of the device at these or any other conditions beyond those indicated in the operational sections of the specifications are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

NOTE1: Repetitive Rating: Pulse width limited by the Maximum junction temperature

NOTE2: 1-in² 2oz Cu PCB board



ELECTRICAL CHARACTERISTICS

 $T_A=25$ °C

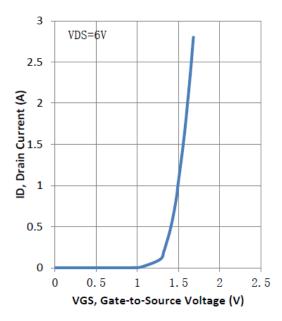
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
STATIC							
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =-250uA -20		-	-	٧	
Gate Threshold Voltage	V _{GS(th)}	$V_{GS} = V_{DS}$, I_D =-250uA	-0.6	-0.85	-1.4	V	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-20V, V _{GS} =0	ı	-	-1	uA	
Gate-to-Source Leakage Current	Igss	V _{DS} =0V, V _{GS} =±12V	-	-	±100	nA	
Drain-to-Source On ResistanceNOTE3	R _{DS(ON)}	V _{GS} =-4.5V, I _D =-4.7A	1	58	70	mΩ	
		V _{GS} =-2.7V, I _D =-3.8A	-	63	90		
		V _{GS} =-2.5V, I _D =-1A	-	75	110		
Forward Diode Voltage	V _{SD}	V _{GS} =0V, I _{SD} =-1.7A	-	-	-1.2	V	
DYNAMIC							
Total Gate Charge	Qg	\\ -40\\\\ -47\\	-	24	36	nC	
Gate-to-Source Gate Charge	Qgs	V _{GS} =-10V,V _{DS} =-4.7V,	-	18	-		
Gate-to-Drain Charge	Q_{gd}	1D=-4.5A	-	2.7	-		
Turn-On Delay Time	t _{d(on)}	V _{DD} =-10V, R _L =10Ω, I _D =-1A, V _{GEN} =-4.5V,	-	22	35	ns	
Rise Time	t _r		-	35	55		
Turn-Off Delay Time	t _{d(off)}		-	45	70		
Fall Time	tf	- R _G =6Ω	-	25	40		
Forward Transconductance	g FS	V _{DS} =-10 V, I _D =-4.7A	ı	8	-	S	

NOTE3: Pulse Test: Pulse width≤300µs, duty cycle ≤2%.

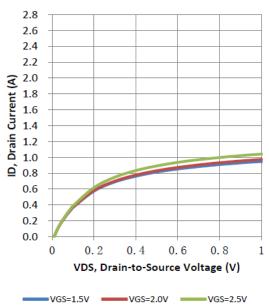


TYPICAL CHARACTERISTICS

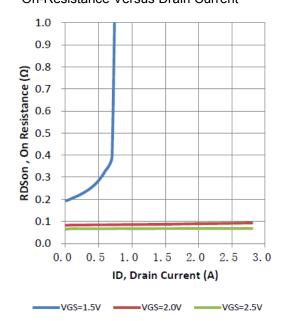
1. Transfer Characteristics



2. On-Region Characteristics



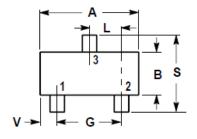
3. On-Resistance Versus Drain Current

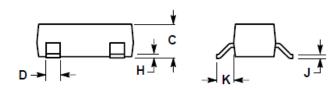


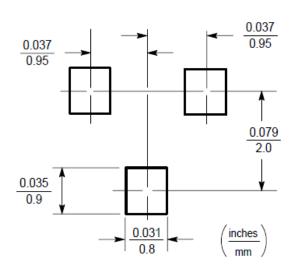
REV1.1

PACKAGE INFORMATION

Dimension in SOT-23S Package (Unit: mm)







DIM	MILLIMETERS		INCHES		
	MIN	MAX	MIN	MAX	
А	2.800	3.040	0.1102	0.1197	
В	1.200	1.400	0.0472	0.0551	
С	0.890	1.110	0.0350	0.0440	
D	0.370	0.500	0.0150	0.0200	
G	1.780	2.040	0.0701	0.0807	
Н	0.013	0.100	0.0005	0.0040	
J	0.085	0.177	0.0034	0.0070	
K	0.350	0.690	0.0140	0.0285	
L	0.890	1.020	0.0350	0.0401	
S	2.100	2.640	0.0830	0.1039	
V	0.450	0.600	0.0177	0.0236	

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